Final Product Change Notification | 201610011F01

Issue Date: 09-Nov-2016
Effective Date: 07-Feb-2017

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Management Summary

NXP Semiconductors announces a new stamped leadframe for the ESOIC 32 lead exposed pad devices associated with this notification.

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[X] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage

ESOIC 32 Lead Stamped Leadframe Qualification

Details of this Change

NXP Semiconductors announces the qualification of a stamped leadframe, replacing current etched leadframe, for the ESOIC 32 lead exposed pad devices associated with this notification. These products are now qualified for assembly at NXP-ATTJ assembly site, Tianjin China. The leadframe materials and vendor are identical to previous, however the form of the exposed pad area changed slightly with the new stamped process and resulted in a new case outline. See attached change summary for details, including case outline comparison.

Why do we Implement this Change

The change from etched to stamped leadframe is required for manufacturing optimization and supply assurance.

Identification of Affected Products

There is no change to orderable part number or product identification.

Product Availability

Sample Information

Samples are available from 31-Oct-2016

Production

Planned first shipment 02-Jan-2017

Impact

No change to fit, function or reliability. Only the form of the leadframe exposed pad area shape / dimension changed slightly with the new stamped process.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 09-Dec-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
MC17XSF400EK	MC17XSF400EK	MC17XSF400EK	QUAD HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC10XS6200EK	MC10XS6200EK	MC10XS6200EK	QUAD HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC22XSD200BEK	MC22XSD200BEK	MC22XSD200BEK	36V 22MOHM DUAL HI SIDE	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC25XS6300EK	MC25XS6300EK	MC25XS6300EK	TRIPLE HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC40XSF500EK	MC40XSF500EK	MC40XSF500EK	PENTA HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC10XS6325EK	MC10XS6325EK	MC10XS6325EK	QUAD HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC08XS6421EK	MC08XS6421EK	MC08XS6421EK	QUAD HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC10XS6225EK	MC10XS6225EK	MC10XS6225EK	QUAD HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC22XS4200BEK	MC22XS4200BEK	MC22XS4200BEK	24V 22MOHM DUAL HI SIDE	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC50XSD200BEK	MC50XSD200BEK	MC50XSD200BEK	36V 50MOHM DUAL HI SIDE	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC17XS6400EK	MC17XS6400EK	MC17XS6400EK	QUAD HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC17XSG500EK	MC17XSG500EK	MC17XSG500EK	PENTA HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	CQS	BL power MOS
MC50XS4200BEK	MC50XS4200BEK	MC50XS4200BEK	24V 50MOHM DUAL HI SIDE	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS
MC08XSF421EK	MC08XSF421EK	MC08XSF421EK	QUAD HIGH SIDE SWITCH	ESOIC 32 7.5*11*2.3 P.65	ESOIC 32 7.5*11*2.3 P.65	RFS	BL power MOS